PCN Number:		2017120500	1	PCN Date:		December 06, 2017			
Title: Datasheet for LMX2592									
Cust	tomer Contact:	PCN Manager			De	pt:	Quality Services		
Change Type:									
	Assembly Site		Design				⁻ Bump Site		
	Assembly Process					Wafer Bump Material			
	Assembly Materials			nber change			Bump Process		
	Mechanical Specification		Test Site			Wafer Fab Site			
	Packing/Shipping/	Labeling	Test Pro	cess			Fab Materials		
			on Dotoile		Wafer Fab Process				
Notification Details Description of Change:									
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. LMX2592 SNAS646F-DECEMBER 2015-REVISED NOVEMBER 2017									
Changes from Revision E (July 2017) to Revision F Page • Switched the RFoutBP and RFoutBM pins in the pinout diagram									
Changed register 7 and the register descriptions of 4, 20 and 46 19									
The datasheet number will be changing.									
Device Family			Change From:		Change To:		e To:		
LM	LMX2592		SNAS	SNAS646E		SNAS646F			
These changes may be reviewed at the datasheet links provided.									
http://www.ti.com/product/LMX2592									
Reason for Change:									
To accurately reflect device characteristics.									
Anti	icipated impact o	n Fit, Form, I	Function,	Quality or Reli	abilit	y (posi	itive / negative):		
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.									
Changes to product identification resulting from this PCN:									
None.									
Product Affected:									
	X2592RHAR	LMX2592RH	IAT						
		1		I		1			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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